



## Lead Free Solder Wire "Sn99.3Cu0.7"

### Incorporated Flux EG

A high quality binary alloy for mechanical or electrical applications which demand lead free solders on difficult-to-solder surfaces composed of tin and copper it is an efficient suitable alternative to Tin/Lead. Other benefits are increased joint strength. It is highly recommended that all residues are removed after soldering..

#### Chemical Characteristics

Tin-Copper binary Alloy

Amount of Tin:	Sn 99.3 ± 0.2 %
Amount of Copper:	Cu 0.7 ± 0.2 %

Tin and lead of first smelting, copper purity of 99.90%

Chart of typical maximum impurities:

Sb	Pb	Ag	Cd	Bi
0.05	0.05	0.005	0.002	0.01

Fe	Zn	Al	As	Others
0.02	0.001	0.001	0.01	0.05

Available types of incorporated flux:

**Rosin Halide Free:** R1

**Rosin Mildly Activated:** CT2

**Rosin Activated:** A11

**Synthetic Halide Free:** S45V

**Hydro soluble:** HC2 -HC3 - **EG**

**Others:** please consult us.

Amount of flux incorporated: **2.5 +/- 0.3%**

#### Physical Characteristics, standard:

<b>*ALLOY: Sn99.3Cu0.7</b>	
Melting point	227°C (Eutectic)
Specific weight	7.3 g/cm <sup>3</sup>
Wire diameter	From 0.5mm to 5mm
Working temperature	350 to 450 °C

#### \*FLUX EG

- Halide: 10 %
- Residues must be cleaned after soldering
- Use: on Zinc, Nickel, Stainless steel...

#### Other Characteristics

**Supplied on spools:** 500g, 1Kg and 3kg others on request

**Packed in cartons of:** 10Kg and 18Kg

**Identification:** Boxes and spools carry product information labels

**Quality assurance:** Certificates of Conformity can be issued for each shipment batch if requested at the time of ordering.

**Storage:** In original packaging at room temperature for 12 months